# 1-104068-3 O DO NOT USE FOR NEW DESIGN

### AMPMODU | AMPMODU System 50

TE Internal #: 1-104068-3

PCB Mount Header, Vertical, Board-to-Board, 34 Position, 1.27 mm [.05 in] Centerline, Fully Shrouded, Gold (Au), AMPMODU System

50

View on TE.com >



Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Type: PCB Mount Header

PCB Mount Orientation: Vertical
Connector System: Board-to-Board

Number of Positions: **34**Number of Rows: **2** 

### **Features**

### **Product Type Features**

PCB Connector Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Fully Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Connector Product Type	Connector Assembly

## **Configuration Features**

Connector Contact Load Condition	Fully Loaded
Board-to-Board Configuration	Parallel
PCB Mount Orientation	Vertical
Number of Positions	34
Number of Rows	2

#### **Electrical Characteristics**

Operating Voltage	30 VAC
Insulation Resistance	5000 MΩ
Dielectric Withstanding Voltage (Max)	500 VAC

## **Body Features**

Connector Profile	Standard	



Primary Product Color	Black		
Contact Features			
Contact Underplating Material	Nickel		
PCB Contact Termination Area Plating Material Finish	Matte		
Contact Mating Area Plating Material Thickness	.76 μm[30 μin]		
Mating Square Post Dimension	.38 mm[.015 in]		
PCB Contact Termination Area Plating Material Thickness	3.81 – 6.35 μm[150 – 250 μin]		
Contact Shape & Form	Rectangular		
Contact Base Material	Copper Alloy		
PCB Contact Termination Area Plating Material	Tin-Lead		
Contact Mating Area Plating Material	Gold (Au)		
Contact Type	Pin		
Contact Current Rating (Max)	3.6 A		
Termination Features			
Termination Post & Tail Diameter	.38 mm[.015 in]		
Termination Post & Tail Length	2.54 mm[.1 in]		
Termination Method to PCB	Through Hole - Solder		
Mechanical Attachment			
Mating Retention Type	Latch		
Mating Retention	With		
Mating Alignment Type	Polarization		
PCB Mount Retention	Without		
PCB Mount Alignment	Without		
Connector Mounting Type	Board Mount		
Mating Alignment	With		
Housing Features			
Housing Material	LCP		
Centerline (Pitch)	1.27 mm[.05 in]		
Dimensions			
Row-to-Row Spacing	2.54 mm[.1 in]		
PCB Thickness (Recommended)	1.57 mm[.062 in]		
Usage Conditions			



Housing Temperature Rating	High	
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]	
Operation/Application		
Solder Process Feature	Board Standoff	
Circuit Application	Signal	
Industry Standards		
Compatible With Agency/Standards Products	CSA, UL	
UL Rating	Recognized	
Compatible With Approved Standards Products	CSA LR7189, UL E28476	
UL Flammability Rating	UL 94V-0	
Packaging Features		
Packaging Quantity	19	
Packaging Method	Box, Tube	
Other		
Position Locations Omitted	0	

## **Product Compliance**

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Not Compliant
EU ELV Directive 2000/53/EC	Compliant with Exemptions
China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247)  Candidate List Declared Against: JAN 2025 (247)  SVHC > Threshold:  Pb (13% in 4690971273)  Article Safe Usage Statements:  Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Wave solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as



EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

## Compatible Parts

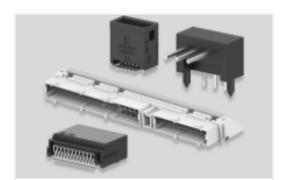




## Also in the Series | AMPMODU System 50



Board-to-Board Headers & Receptacles(685)



PCB Headers & Receptacles(685)



Rectangular Power Connectors(47)

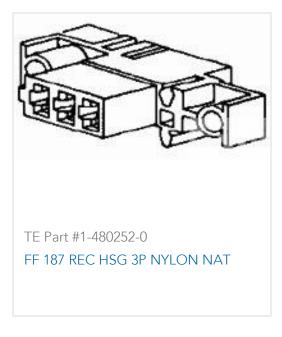


Wire-to-Board Headers & Receptacles (47)

## **Customers Also Bought**









PCB Mount Header, Vertical, Board-to-Board, 34 Position, 1.27 mm [.05 in] Centerline, Fully Shrouded, Gold (Au), AMPMODU System 50

















## **Documents**

## **Product Drawings**

34 SYSTEM 50 HDR DRST SHRD

English

### **CAD Files**

3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_1-104068-3\_S.2d\_dxf.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_1-104068-3\_S.3d\_igs.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_1-104068-3\_S.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

**Product Specifications** 

**Application Specification** 

English